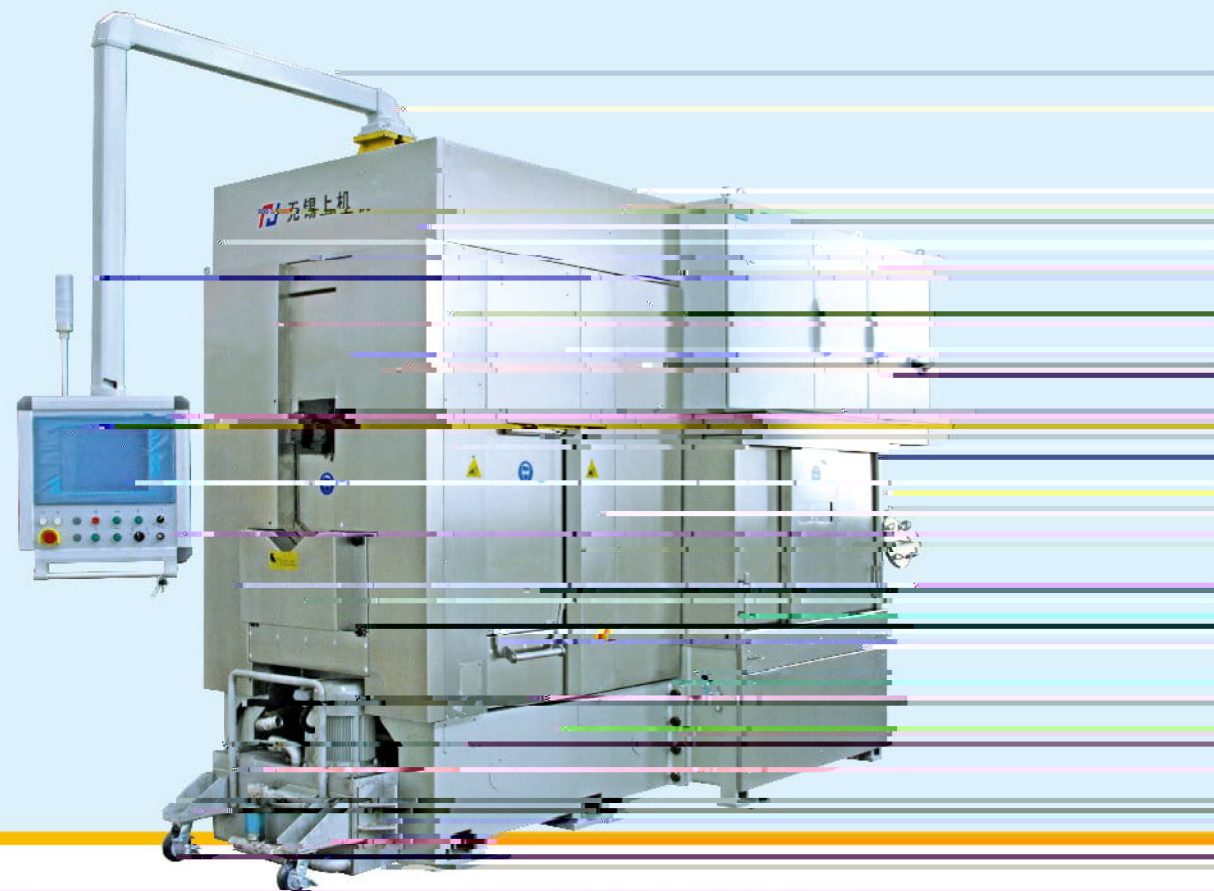


WSK060 蓝宝石切片机

WSK060 Sapphire Slicing Machine



技术规格参数 Specifications and Technical Parameters

规格 Specification	尺寸规格 (mm)
长度 Length	600mm
厚度 Thickness	>8.2mm

主要参数 Main Parameters

导轮直径 Guide wheel diameter	220mm
导轮轴距 Guide wheel base	440mm
导轮长度 Guide wheel length	360mm
送料速度 Feed rate	0.01mm/2200mm/min
摇摆角度 Swinging angle	±12°
切割方向 Cutting direction	前进或后退切割/双向切割 forward or reverse cutting/two-way cutting
存储容量 Storage capacity	220mm
水箱容量 Water tank capacity	200L

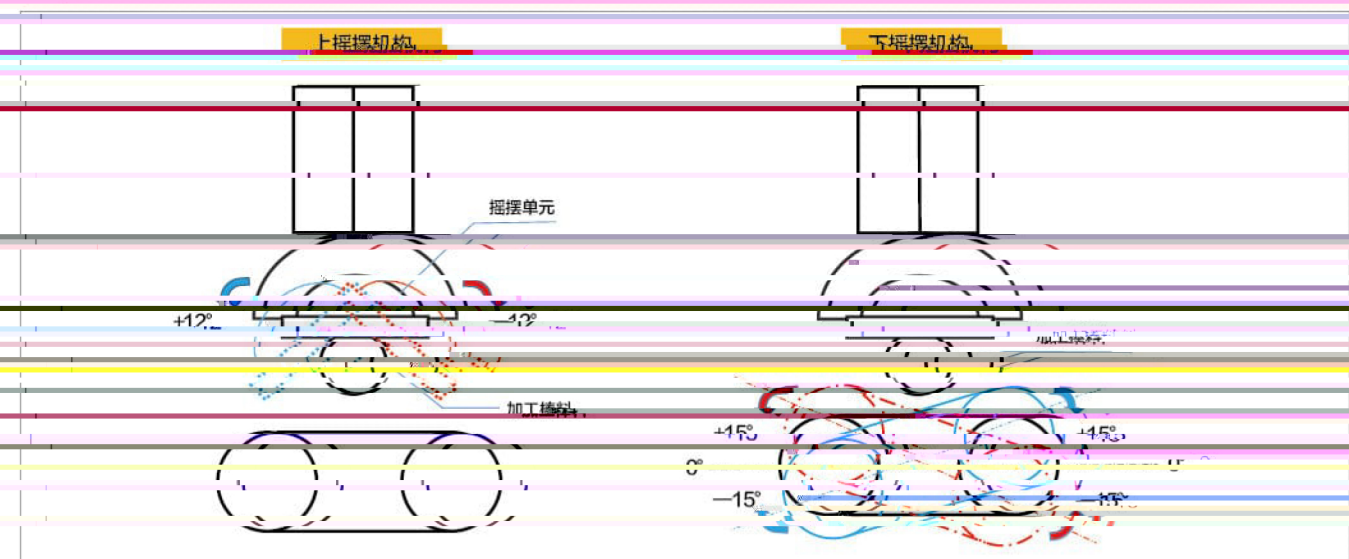
能源供应 Power supply

电源功率 Power consumption	220V/50Hz/30A
平均功率 Average power	35kW
冷却水温度 Cooling water	10~17°C

外形尺寸 Dimensions

机床外形尺寸 (长*宽*高) Equipment size (L*W*H)	1600*2200*2200mm
机床重量 weight	≈ 12000kg

示意图 Sketch



设备用途与性能特征

- 本机床用于自动切割长条、坚硬、易脆材料，使用金刚石刀具切割硅、锗、石英玻璃、陶瓷、蓝宝石晶体等。
- 机床所有电器元件均采用国际国内知名品牌，保证机床的稳定性。
- 采用西门子控制技术的一体化PC机，15"触摸屏。
- 电控柜配备独立温控系统，保证各控制元件正常工作。
- 设备具备摇摆功能，双支撑摇摆单元优化了金刚石切割蓝宝石的性能，缩短了切割时间，并提高了晶片的质量。
- 滑轮数量最少化设计（仅6个滑轮），减少刚线扭曲和疲劳。

Applications and Features

- This machine is used to automatically cut long, hard, brittle materials using diamond tools to cut silicon, germanium, quartz glass, ceramics, sapphire crystals, etc.
- All electrical components apply international and domestic outstanding brands to ensure the stability of the machine.
- Apply integrated PC of SIEMENS simotion controlling system, 15" touch screen
- The electric control cabinet is equipped with independent temperature control system to ensure the normal operation of each control component.
- The equipment features swinging function, and the dual support swinging unit optimizes the performance of diamond wire saw application, shortens the cutting time, and improves the wafer quality.
- Minimal design number of pulleys (only 6 pulleys) to reduce wire distortion and fatigue.